Surface Mount Trench Schottky Power Rectifier

POWERMITE® Power Surface Mount Package

Features

- Low Profile Maximum Height of 1.1 mm
- Small Footprint Footprint Area of 8.45 mm²
- Supplied in 12 mm Tape and Reel
- Low Thermal Resistance with Direct Thermal Path of Die on Exposed Cathode Heat Sink
- Fine Lithography Trench-based Schottky Technology for Very Low Forward Voltage and Low Leakage
- Fast Switching with Exceptional Temperature Stability
- Low Power Loss and Lower Operating Temperature
- Higher Efficiency for Achieving Regulatory Compliance
- High Surge Capability
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These are Pb-Free and Halide-Free Devices

Typical Applications

- Switching Power Supplies including Adapters & Flat Panel Displays
- High Frequency and DC–DC Converters
- Freewheeling and OR-ing diodes
- Reverse Battery Protection
- Instrumentation

Mechanical Characteristics:

- Powermite is JEDEC Registered as D0-216AA
- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 16.3 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds



ON Semiconductor®

www.onsemi.com

SCHOTTKY TRENCH RECTIFIER 2.0 AMPERES, 45 VOLTS



POWERMITE CASE 457

MARKING DIAGRAM



M = Date Code
E24 = Device Code
Pb-Free Package
(Marking Style 1)

ORDERING INFORMATION

Device	Package	Shipping [†]
NRVTSM245ET1G	Powermite (Pb-Free)	3000 / Tape & Reel
NRVTSM245ET3G	Powermite (Pb-Free)	12000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating		Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	45	V
Average Rectified Forward Current (T _L = 168°C)	Io	2.0	Α
Peak Repetitive Forward Current (Square Wave, 20 kHz, T _L = 167°C)	I _{FRM}	4.0	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	50	Α
Storage and Operating Junction Temperature Range (Note 1)	T _{stg} , T _J	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2)	Ψ_{JCL}	6.3	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{ heta JA}$	82	°C/W
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{ heta JA}$	200	°C/W

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 4) (I _F = 2 A, T _J = 25°C)	V _F	0.65	V
(I _F = 2 A, T _J = 125°C) Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, T _J = 25°C)	I _R	0.58 75	uА
(Rated do Voltage, T _J = 125°C)		3	mΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics for the listed test conditions.

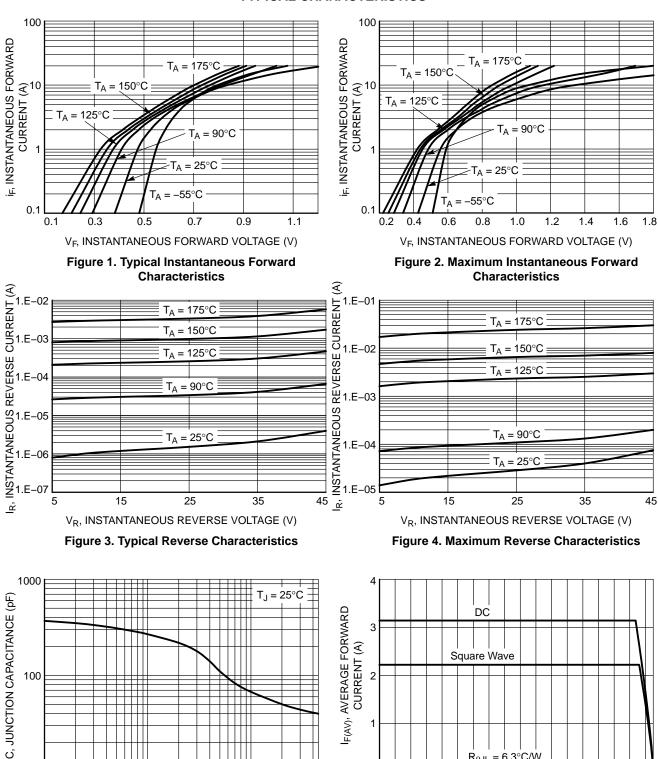
2. Mounted with 700 mm² copper pad size (Approximately 1 in²) 1 oz FR4 Board.

3. Mounted with pad size approximately 20 mm² copper, 1 oz FR4 Board.

4. Pulse Test: Pulse Width ≤ 380 μs, Duty Cycle ≤ 2.0%.

^{1.} The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

TYPICAL CHARACTERISTICS



V_R, REVERSE VOLTAGE (V) Figure 5. Typical Junction Capacitance

0.1

T_C, LEAD TEMPERATURE (°C) Figure 6. Current Derating

90

110

150

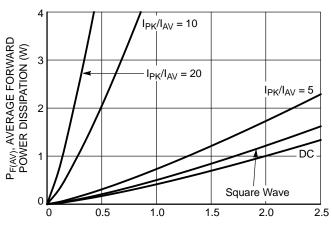
170

 $R_{\theta JL} = 6.3^{\circ}C/W$

70

10

TYPICAL CHARACTERISTICS



I_{F(AV)}, AVERAGE FORWARD CURRENT (A)

Figure 7. Forward Power Dissipation

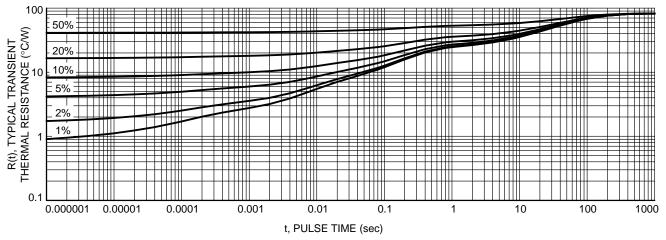
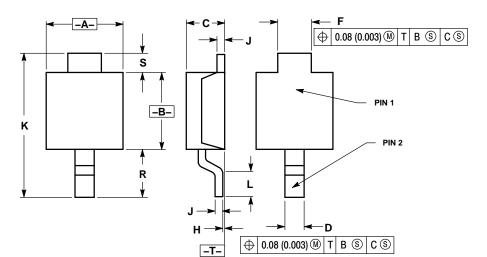


Figure 8. Thermal Response, Junction-to-Ambient

PACKAGE DIMENSIONS

POWERMITE

CASE 457-04 ISSUE F

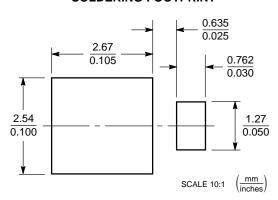


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.

 - DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.75	2.05	0.069	0.081
В	1.75	2.18	0.069	0.086
С	0.85	1.15	0.033	0.045
D	0.40	0.69	0.016	0.027
F	0.70	1.00	0.028	0.039
Н	-0.05	+0.10	-0.002	+0.004
J	0.10	0.25	0.004	0.010
K	3.60	3.90	0.142	0.154
L	0.50	0.80	0.020	0.031
R	1.20	1.50	0.047	0.059
S	0.50 REF		0.019 REF	

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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